



PATENT

S/N 09/643,526

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Tongbi Jiang et al.  
Serial No.: 09/643,526  
Filed: August 22, 2000  
Title: CIRCUIT BOARD

Examiner: Hung S. Bui  
Group Art Unit: 2841  
Docket: 303.705US1

#10/Amt A  
R. Tuy  
10/31/02

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OCT 30 2002

AMENDMENT AND RESPONSE UNDER 37 C.F.R. § 1.111

Commissioner for Patents  
Washington, D.C. 20231

Applicant has reviewed the office action mailed on June 19, 2002. Please amend the above-identified patent application as follows.

IN THE CLAIMS

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect amendment of previously pending claims 8 and 9. The specific amendments to individual claims are detailed in the following marked up set of claims.

8. (Amended) The circuit board of claim 7, wherein the core layer has greater mechanical strength [that] than the first layer.
  
9. (Amended) The circuit board of claim 7, wherein the core layer has greater mechanical strength [that] than the second layer.

REMARKS

Applicant has carefully reviewed and considered the Office Action mailed on June 19, 2002 and the references cited therewith.

Claims 8 and 9 are amended, no claims are canceled, and no claims are added; as a result, claims 1-25 are now pending in the application. Claims 8 and 9 are amended to correct a typographical error. Claims 8 and 9 were not amended in response to a rejection based on prior art. No new matter is added by the amendments.